

METHOD FOR BONDING HEAT SINKS TO OVERMOLD MATERIAL

ABSTRACT

A method and resulting electronic package in which a heat sink is secured to the package's dielectric material (e.g., overmold). The surface of the dielectric is roughened (e.g., using an abrasive paper or pad) to enhance the subsequent dielectric-heat sink bond in which an adhesive is used. The dielectric material's roughened external surface(s), typically containing silicone material (e.g., silicone residue) which is an inherent by-product of many dielectric materials of the type used in such packaging, is (are) able to still be securely attached to the heat sink, despite the presence of said silicone. In another embodiment, the roughened surface enhances the marking of dielectric material of this type (e.g., using ink).